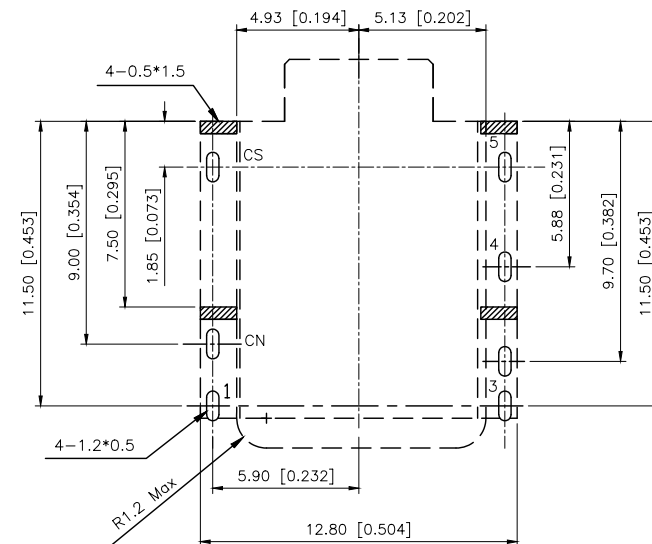
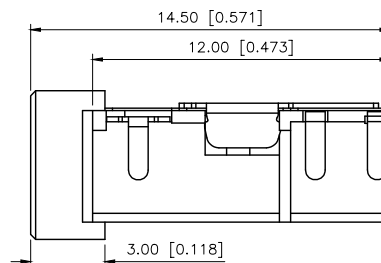
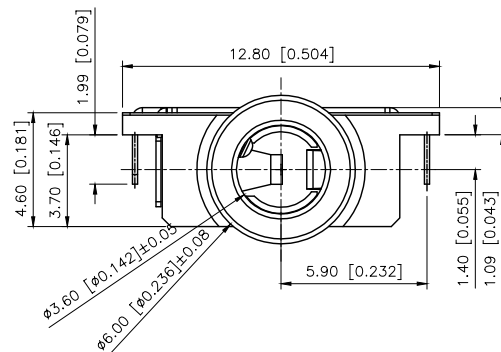
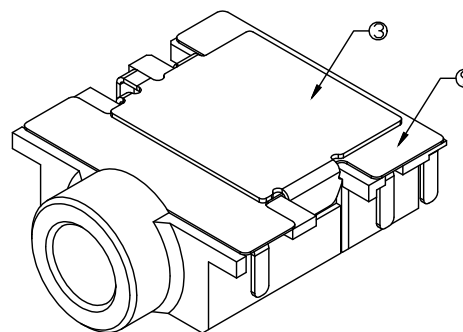
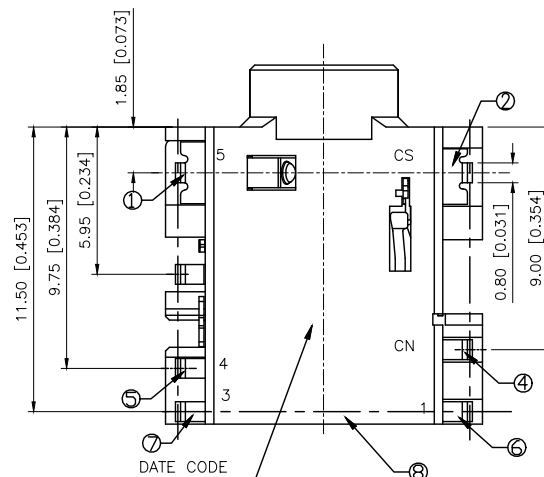
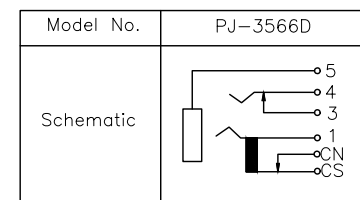


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.06.26	阿树



PCB LAYOUT TOP VIEW
TOLERANCES: ±0.05



⑨	Mylar	1		Black
⑧	Housing	1	Hich temp. Thermoplastic	Black
⑦	Terminal 7#	1	Copper Alloy	Au-Plated
⑥	Terminal 6#	1	Copper Alloy t=0.20	Au-Plated
⑤	Terminal 5#	1	Copper Alloy t=0.20	Au-Plated
④	Terminal 4#	1	Copper Alloy t=0.20	Au-Plated
③	Shell	1	SUS301 t=0.20	Ni-Plated
②	Terminal 2#	1	Copper Alloy t=0.20	Au-Plated
①	Terminal 1#	1	Copper Alloy t=0.20	Au-Plated
No.	PART NAME	QTY	MATERIAL(THICK)	PLATING(COLOR)

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



DESIGN	阿树	VIEW:	MODEL TYPE: 3.5 PHONE JACK
CHECKED		UNIT: mm/in	PART NO.: PJ-3566D
APPROVED		SIZE: A4	DWG NO.: X-PJ-3566D